



Features
of the
KE-2000
series

Laser
centering

Vision
centering

Feature

The ultra-flexible KE-2060 can place a wide range of components from 0603 and ICs, to odd-form, all at a high rate of speed.

- 12,500CPH: chip (laser centering/effective tact)
- 1,850CPH: IC (vision centering/effective tact), 3,400CPH with MNVC option.
- One multi-nozzle laser head (4 nozzles) plus one high resolution head (1 nozzle)
- from 0603 (0201) to 74mm square components or 50×150mm 0402 (01005) option factory installed.
- Vision centering system (featuring bottom, side, and back lighting, ball recognition and split recognition)

※1 Actual throughput may vary.

※2 Please download brochure for details.

Specifications

Board size	M size (330×250mm)	○
	L size (410×360mm)	○
	L-wide (510×360mm)	○
	E size (510×460mm)*1	○
Component size	Laser recognition	0603 (0201) ~ □20mm or 26.5×11mm (0402 (01005) optional)*5
	Vision recognition	1.0×0.5mm*2 ~ □20mm or 26.5×11mm
Placement speed	Chip	12,500CPH*2
	IC	3,290CPH*3
Placement accuracy	Laser recognition	±0.05mm
	Vision recognition	±0.04mm
Feeder inputs		Max. 80 on 8mm T/F*4

*1 Production arrangement starts only after receipt of P/O for E size board.

*2 Effective tact: The chip placement speed indicates an estimated value obtained when the machine places 400 1005-chips all over an M size board.
(CPH = number of components placed for one hour)

*3 Estimated value when using MNVC and picking up components simultaneous with all nozzles.

*4 In addition to matrix tray changer, max 110.

*5 Please ask for details on 0402(01005) placement.